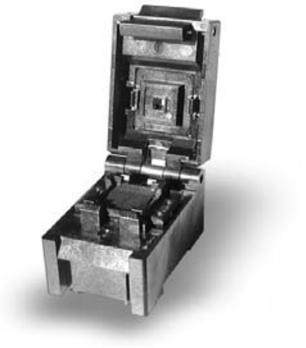
IC409 Series (Clamshell Chip Scale Package - SMT (CSP, 0.50mm Pitch)

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	–40°C to +150°C
Contact Force:	58.8mN (6gf) per pin approx.
Actuation Force:	19.6N (2kg) max.

Part Number (Details)

Please Contact Yamaichi



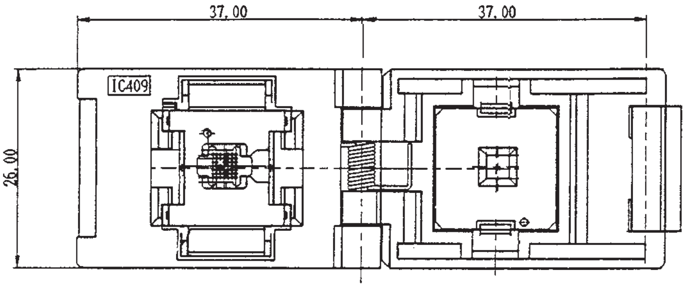
Materials and Finish

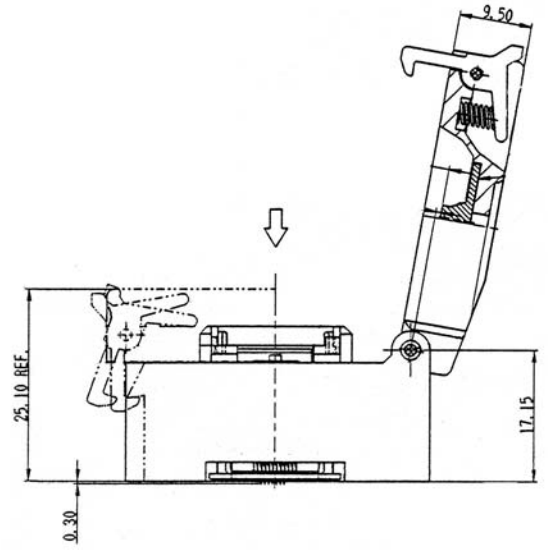
Housing:	Polyetherimide (PEI), glass-filled Polyetherssulphone (PES), glass-filled
Contacts:	Beryllium Copper (BeCu)
Plating:	Gold over Nickel

Features

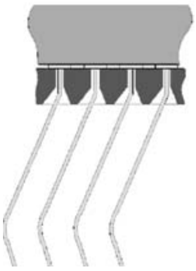
- Clamshell socket for BGA / LGA / CSP packages with 0.50mm pitch
- TH soldering (0.50mm pitch)
- 20 x 20 maximum grid size
- Body size 11.024 x 11.024mm
- Depopulation versions available

Outline Socket Dimensions



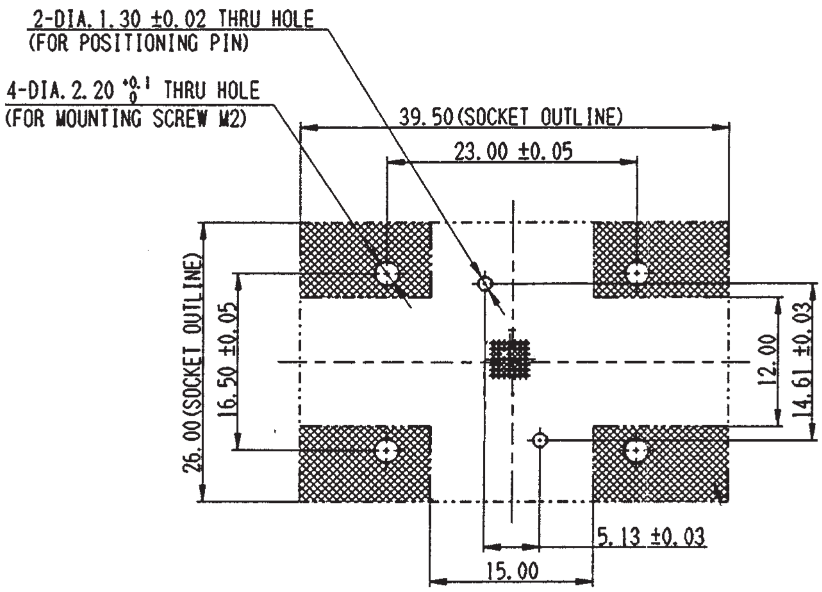


Bow Style Contacts



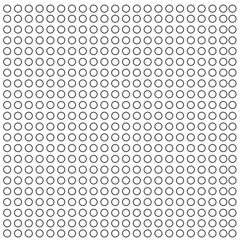
Recommended PC Board Layout

Top View from Socket



Typical IC Grid Size 22x22

Body Size: 11.024 x 11.024



IC409 Series (Clamshell) Chip Scale Package - TH (CSP, 0.50mm Pitch)

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	–40°C to +150°C
Contact Force:	58.8mN (6gf) per pin approx.
Actuation Force:	19.6N (2kg) max.

Part Number (Details)

Please Contact Yamaichi

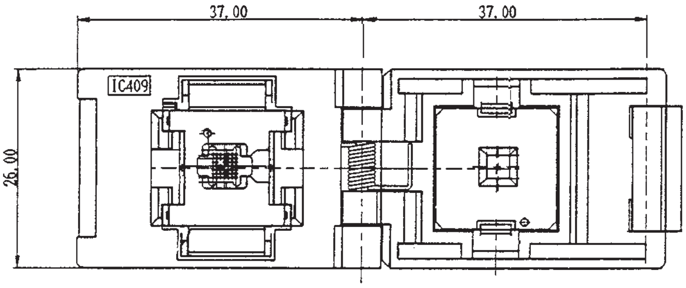
Materials and Finish

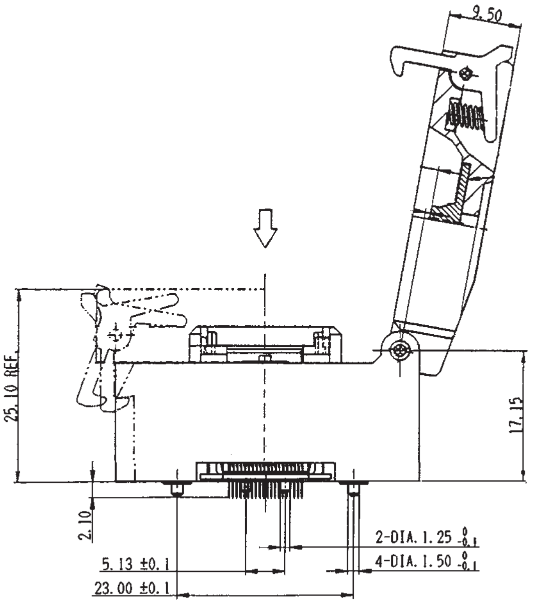
Housing:	Polyetherimide (PEI), glass-filled Polyetherssulphone (PES), glass-filled
Contacts:	Beryllium Copper (BeCu)
Plating:	Gold over Nickel

Features

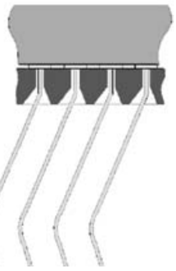
- ➩ Clamshell socket for BGA / LGA / CSP packages with 0.50mm pitch
- ➩ TH soldering (0.50mm pitch)
- ➩ 20 x 20 maximum grid size
- ➩ Body size 11.024 x 11.024mm
- ➩ Depopulation versions available

Outline Socket Dimensions

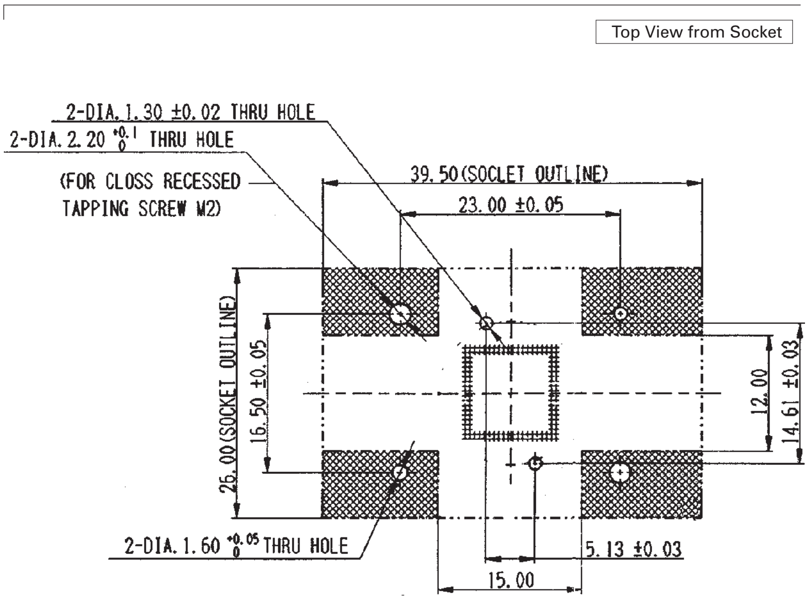




Bow Style Contacts



Recommended PC Board Layout



Typical IC Grid Size 22x22

Body Size: 11.024 x 11.024